

DWG. NO. SD-55686-012

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DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

F

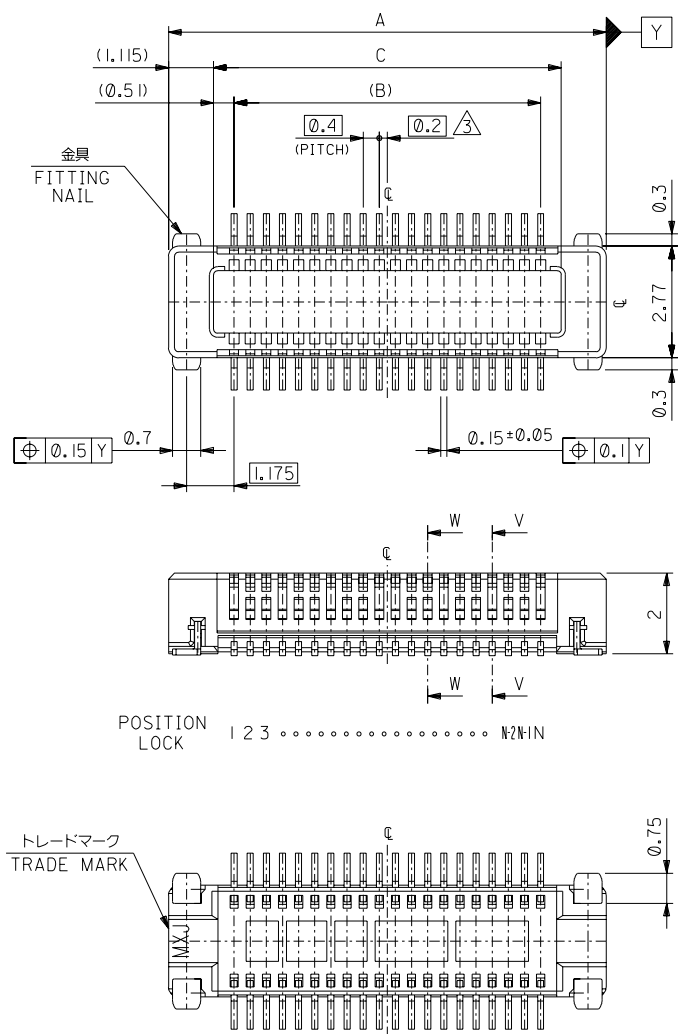
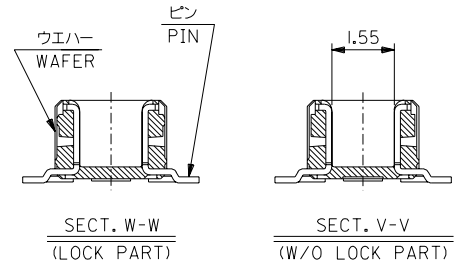
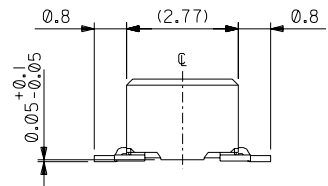
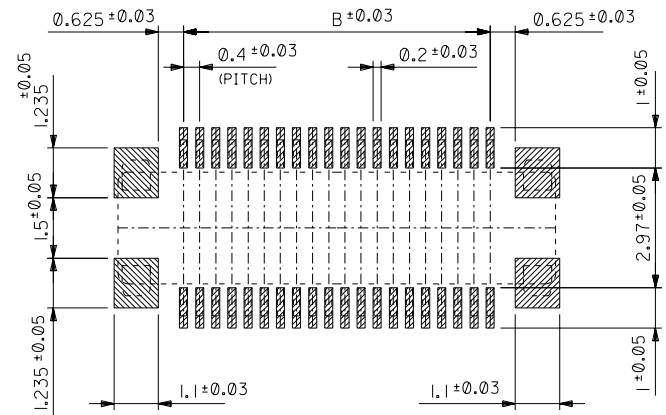
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SD-55686-012.S01



参考基板レイアウト (マウント面)
P.C.BOARD PATTERN DIMENSION (REFERENCE)
(MOUNTING SIDE)

NONE	24.62	23.6	26.85	55686-1273	120
2,3,5,6,8,9,12,13,15,16,18,19	8.62	7.6	10.85	55686-0473	40
LOCK POSITION	C	B	A	MATERIAL NO.	CKT.

MODEL NO.	55686-0473	DIMENSIONS:	SHT	REV
DESIGN UNITS	THIRD ANGLE PROJECTION	☐ mm ☐ INCH ☒ mm ONLY	REVISION	ON CAD ONLY
DRAWN BY & DATE	H.KAWABATA '04/03/11	TITLE:	0.4 B-To-B PLUG Assy WITHOUT BOSS (Hg+=2.5-3) -LEAD REE-	
CHECKED BY & DATE	K.TOJO '04/03/11	MOLEX INCORPORATED		
APPROVED BY & DATE	M.SASAO '04/03/11	MATERIAL NO.	DRAWING NO.	SHEET NO.
CAD FILENAME	SD-55686-012.S01	SEE CHART	SD-55686-012	1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		RELEASED '04/03/11 EC NO. J2004-3038 DRWN: H.KAWABATA CHK: K.TOJO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
							FINISH 仕上げ	—//—		10 UNDER 未満	±0.2
										10 OVER 30 UNDER 以上 未満	±0.25
										30 OVER 以上	±0.3
										ANGLE 角度	±3°
REV	INS. RANGE 被覆外径	—//—									

8 7 6 5 4 3 2 1 EN-02J(097) MXJ-54

DWG. NO.
SD-55686-012

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DO NOT SCALE DRAWING

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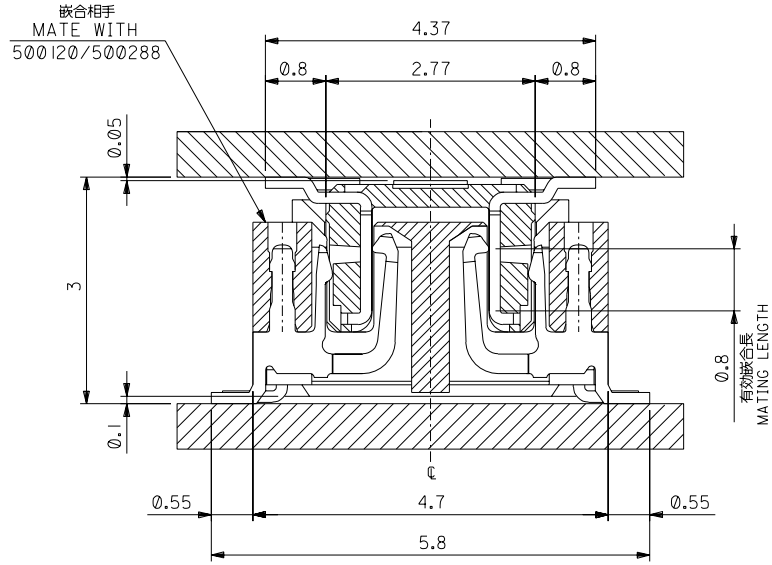
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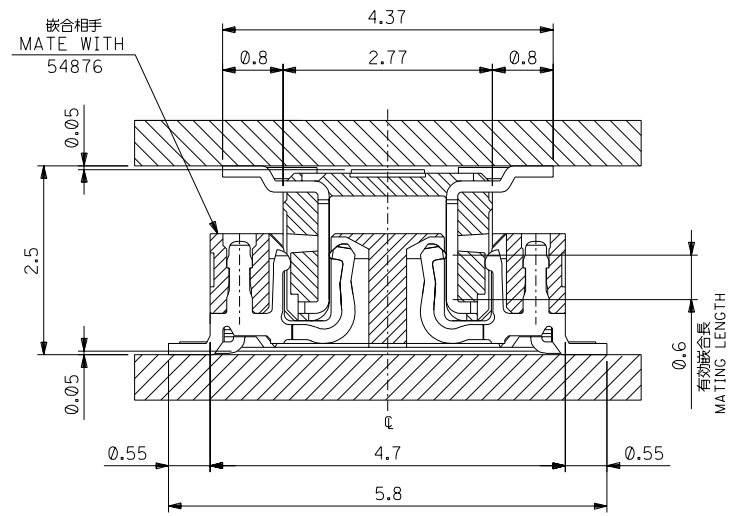
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SD-55686-012.92



嵌合高さ : 3mm
嵌合断面図 (参考)
MATED DRAWING (REFERENCE)
(MATED HEIGHT : 3mm)



嵌合高さ : 2.5mm
嵌合断面図 (参考)
MATED DRAWING (REFERENCE)
(MATED HEIGHT : 2.5mm)

注記 NOTES

1. 使用材料 MATERIAL

ウエハー : 液晶ポリマー (LCP), ガラス充填, UL94V-0 (黒)
WAFER : LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0 (COLOR : BLACK)

ピン : 黄銅 (t=0.15)

PIN : BRASS

金具 : リン青銅 (t=0.15)

FITTING NAIL : PHOSPHOR BRONZE

2. メッキ仕様 PLATING

ピン PIN

金メッキ 0.1マイクロメートル以上 (コンタクト部)

GOLD 0.1MICROMETER MINIMUM (CONTACT AREA)

金メッキ 0.4マイクロメートル以下 (テール部)

GOLD 0.4MICROMETER MAXIMUM (TAIL AREA)

下地メッキ : ニッケルメッキ 1.5マイクロメートル以上

UNDER PLATING : NICKEL 1.5MICROMETER MINIMUM

金具 PIN

錫メッキ 1.0マイクロメートル以上
TIN 1.0MICROMETER MINIMUM

下地メッキ : ニッケルメッキ 1.0マイクロメートル以上

UNDER PLATING : NICKEL 1.0MICROMETER MINIMUM

△ (金種数/2) = 偶数の場合に適用。

APPLY FOR (CIRCUIT/2)=EVEN

4. 嵌合相手 : 500120/500288/54876シリーズ
MATE WITH : 500120 / 500288 / 54876 SERIES

5. テール平坦度は0.08以下、
テール及び金具の平坦度は0.1以下
TAIL COPLANARITY TO BE 0.08MAXIMUM.
TAIL AND FITTING NAIL COPLANARITY TO
BE 0.1MAXIMUM.

6. 本製品は55686-***3の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55686-***3.

注記参照
SEE NOTES

FINISH 仕上げ //

WIRE RANGE 適用電線範囲 //

INS. RANGE 被覆外径 //

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
一般公差

10 UNDER 未満 ±0.2

10 OVER 以上 30 UNDER 未満 ±0.25

30 OVER 以上 ±0.3

ANGLE 角度 ±3°

SCALE 1:1

DRAWN BY & DATE
H.KAWABATA '04/03/11

CHECKED BY & DATE
K.TOJO '04/03/11

APPROVED BY & DATE
M.SASAO '04/03/11

CAD FILENAME
SD-55686-012.S02

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MODEL NO.

55686-***73

DIMENSIONS:

☐ mm ☐ INCH ☒ mm ONLY

SHT REV

REVISE ON CAD ONLY

THIRD ANGLE PROJECTION

TITLE:
0.4 B-To-B Plug Assy WITHOUT BOSS
(Hg+=2.5-3) -LEAD FREE-

MOLEX MOLEX INCORPORATED

MATERIAL NO.
SEE CHART

DRAWING NO.
SD-55686-012

SHEET NO.
2 OF 2

EN-02J(097) MXJ-54